

1. (Three times amended) A semiconductor die and strapless lead frame/heat slug combination, comprising:

lead frame leads, all of said leads being evenly distributed around a semiconductor die mount area;

a heat slug providing the die mount area, wherein said heat slug is attached under the lead frame with tape; and

said semiconductor die mounted on said heat slug, wherein bond pads on said semiconductor die are attached to said lead frame leads with bond wires.

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Note

2. (~~Twice amended~~) The strapless lead frame according to Claim 1, wherein the semiconductor die has four sides and corners, and the lead frame leads are all evenly distributed on each of the four sides and around the corners.

3. The strapless lead frame according to Claim 1, wherein the lead frame has four sides and two of said four sides have a different number of leads from two other sides.

4. (Twice amended) The strapless lead frame according to Claim 1, wherein said semiconductor die has a different number of bond pads on adjacent sides, and at least one of said bond pads is attached to a bond wire, said bond wire is attached to a lead frame lead on a side of the lead frame adjacent to the side of the semiconductor die on which the bond pad is located

5. (Three times amended) A semiconductor die and strapless lead frame combination, comprising:

lead frame leads, all of said leads being evenly distributed around a semiconductor die mount area;

a heat slug providing a rectangular die mount area, wherein said heat slug is attached under the lead frame with tape, there being the same number of lead frame leads on opposite sides of the lead frame and a different number of lead frame leads on adjacent sides of the lead frame; and

said semiconductor die mounted on said heat slug, wherein bond pads on said semiconductor die are attached to said lead frame leads with bond wires.

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6. (Twice amended) The strapless lead frame according to Claim 5, wherein said semiconductor die has a different number of bond pads on adjacent sides and the same number of bond pads on opposite sides, and at least one of said bond pads is attached to a bond wire, said bond wire is attached to a lead frame lead on a side of the lead frame adjacent to the side of the semiconductor die on which the bond pad is located.

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Please add the following new claim:

7. (new) A packaged semiconductor device, comprising:

a unitary lead frame comprising leads arranged around a central die mounting region, said lead frame having four sides with leads having outer ends arranged on said four sides and inner ends all of which are evenly spaced around said central die mounting region;

a heat slug, said heat slug attached to a bottom surface of said lead frame such that said inner ends of said leads overlap said heat slug;

a semiconductor die mounted on said heat slug in said central die mounting region of said lead frame, said die including bond pads arranged along all four edges of said die; and

bond wires coupling said bond pads on said die to said inner ends of said leads.

8. (new) The packaged semiconductor device of Claim 7, wherein said semiconductor die has a different number of bond pads on adjacent sides and the same number of bond pads on opposite sides, and at least one of said bond pads is attached to a bond wire, said bond wire is attached to a lead frame lead on a side of the lead frame adjacent to the side of the semiconductor die on which the bond pad is located.